Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1A**
2. **1Y**
3. **2A**
4. **2Y**
5. **3A**
6. **3Y**
7. **GND**
8. **4Y**
9. **4A**
10. **5Y**
11. **5A**
12. **6Y**
13. **6A**
14. **VCC**

**.031”**

 **1 14**

**13**

**12**

**11**

**10**

**9**

**8**

 **7**

**2**

**3**

**4**

**5**

**6**

**.038”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0034” X .0034”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .031” X .038” DATE: 8/18/21**

**MFG: TEXAS INSTRUMENTS THICKNESS .029” P/N: 54LVC14**

**DG 10.1.2**

#### Rev B, 7/19/02